Refine Search

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Terms	Documents
L4 and ball	9

Database:

US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
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Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search:

L5

Refine Search

Recall Text ⬍   Clear   Interrupt

Search History

DATE: Tuesday, June 22, 2004   Printable Copy   Create Case

Set Name	Query	Hit Count	Set Name
side by side			result set
	DB=USPT; PLUR=YES; OP=ADJ		
L5	L4 and ball	9	L5
L4	L3 and (wire near5 pad)	11	L4
L3	L2 and (passivation near (layer or material or film))	16	L3
L2	L1 and (wire near5 cavity)	297	L2
L1	wire adj bond	7145	L1

END OF SEARCH HISTORY

Hit List

Search Results - Record(s) 1 through 9 of 9 returned.

☐ 1. Document ID: US 6727579 B1

L5: Entry 1 of 9   File: USPT   Apr 27, 2004

US-PAT-NO: 6727579
DOCUMENT-IDENTIFIER: US 6727579 B1

TITLE: ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | | Claims | KWIC | Draw De |

☐ 2. Document ID: US 6478212 B1

L5: Entry 2 of 9   File: USPT   Nov 12, 2002

US-PAT-NO: 6478212
DOCUMENT-IDENTIFIER: US 6478212 B1

TITLE: Bond pad structure and method for reduced downward force wirebonding

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | | Claims | KWIC | Draw De |

☐ 3. Document ID: US 6452406 B1

L5: Entry 3 of 9   File: USPT   Sep 17, 2002

US-PAT-NO: 6452406
DOCUMENT-IDENTIFIER: US 6452406 B1
** See image for Certificate of Correction **

TITLE: Probe structure having a plurality of discrete insulated probe tips

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | | Claims | KWIC | Draw De |

☐ 4. Document ID: US 6336269 B1

L5: Entry 4 of 9   File: USPT   Jan 8, 2002

US-PAT-NO: 6336269
DOCUMENT-IDENTIFIER: US 6336269 B1

TITLE: Method of fabricating an interconnection element

`Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D`

☐ 5.   Document ID: US 6110823 A
L5: Entry 5 of 9   File: USPT   Aug 29, 2000

US-PAT-NO: 6110823
DOCUMENT-IDENTIFIER: US 6110823 A

TITLE: Method of modifying the thickness of a plating on a member by creating a temperature gradient on the member, applications for employing such a method, and structures resulting from such a method

`Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D`

☐ 6.   Document ID: US 5635424 A
L5: Entry 6 of 9   File: USPT   Jun 3, 1997

US-PAT-NO: 5635424
DOCUMENT-IDENTIFIER: US 5635424 A

TITLE: High-density bond pad layout arrangements for semiconductor dies, and connecting to the bond pads

`Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D`

☐ 7.   Document ID: US 5565385 A
L5: Entry 7 of 9   File: USPT   Oct 15, 1996

US-PAT-NO: 5565385
DOCUMENT-IDENTIFIER: US 5565385 A

TITLE: Semiconductor bond pad structure and increased bond pad count per die

`Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D`

☐ 8.   Document ID: US 5441917 A
L5: Entry 8 of 9   File: USPT   Aug 15, 1995

US-PAT-NO: 5441917
DOCUMENT-IDENTIFIER: US 5441917 A

TITLE: Method of laying out bond pads on a semiconductor die

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |

☐ 9. Document ID: US 5404047 A

L5: Entry 9 of 9   File: USPT   Apr 4, 1995

US-PAT-NO: 5404047
DOCUMENT-IDENTIFIER: US 5404047 A

TITLE: Semiconductor die having a high density array of composite bond pads

| Full | Title | Citation | Front | Review | Classification | Date | Reference | | | Claims | KWIC | Draw D |

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